

Integrated Circuit Packaging

2010 Edition

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- MEMS Cost Model - a Microsoft Excel based cost model that uses dropdown menu selections to generate product costs for most MEMS products.
- Discrete and Power Products Cost Model - a Microsoft Excel based cost model that uses dropdown menu selections to generate product costs for most high power silicon integrated circuit and discrete products.
- Integrated Circuit Economics - a report covering the economics of the integrated circuit industry.
- Integrated Circuit Technology - an annual report covering the latest in IC technologies.
- 300mm Watch - a database of 300mm fabs and companion analysis.
- Cleanroom Reference Guide for Semiconductor and MEMS Applications - a concise reference guide containing all the information needed to design, build and operate a cleanroom.
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1.6. Report outline

This report is broken up into 8 chapters:

- Chapter 1 - Welcome
- Chapter 2 - The Packaging Market and History
- Chapter 3 - Package Types
- Chapter 4 - Packaging Process Overview
- Chapter 5 - Packaging Materials
- Chapter 6 - Packaging Technology Trends
- Chapter 7 - Packaging Costs
- Chapter 8 - Test
- Chapter 9 - Qualification
- Chapter 10 - Selecting and Managing Packaging Foundries

1.7. What this report is not

This report is meant to give the reader an understanding of integrated circuit packaging trends.

- We discuss general market trends, but this is not a market research firm and we are not in the business of forecasting the market. For market research and forecasts we recommend IC Insights at www.icinsights.com.
- This report presents some discussion of the economics of the technologies presented, but for a detailed discussion of integrated circuit economics we recommend our IC Economics report.

1.8. About the author

Frank Muscolino is a packaging industry insider with over 20 years of experience. Frank has served in a variety of engineering, management and sales positions within the industry including sales manager for one of the ten largest packaging foundries. Frank has a Masters Degree in Chemistry from Clarkson University.